

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): Lieb et al.  
Serial No.: 10/511,566  
For: PROCESS FOR FORMING A HOUSING FOR ELECTRONIC  
MODULES, AND ELECTRONIC MODULES ECAPSULATED IN  
THIS WAY  
Filed: April 13, 2005  
Examiner: Andrew O. Arena  
Art Unit: 2811  
Confirmation No.: 4191  
Customer No.: 27,623

Attorney Docket No.: 2133.063USU

**Mail Stop ISSUE FEE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450**

**AMENDMENT IN RESPONSE TO  
THE NOTICE TO FILE CORRECTED APPLICATION PAPERS**

Dear Sir:

In response to the Notice to File Corrected Application Papers dated November 9, 2010, please amend the above-identified application as follows:

**Amendments to the Drawings** begin on page **2** of this paper.

**Remarks** begin on page **3** of this paper.